Product Change Notification - GBNG-04NNSN044

Date:

08 Nov 2019

Product Category:

Access Networks

Affected CPNs:

Notification subject:

CCB 3998 and 3998.001 Initial Notice: Qualification of MMT as a new assembly site for selected MSCC LE58QL0xxx device family available in 32L PLCC (11.5x14x3.37mm) and 44L PLCC (16.6x16.6x4.4mm) packages using palladium coated copper with gold flash (CuPdAu) bond wire.

Notification text:

PCN Status:

Initial notification

PCN Type:

Manufacturing Change

Microchip Parts Affected:

Please open one of the icons found in the Affected CPNs section above.

NOTE: For your convenience Microchip includes identical files in two formats (.pdf and .xls).

Description of Change:

Qualification of MMT as a new assembly site for selected MSCC LE58QL0xxx device family available in 32L PLCC (11.5x14x3.37mm) and 44L PLCC (16.6x16.6x4.4mm) packages using palladium coated copper with gold flash (CuPdAu) bond wire.

Pre Change:

Assembled at ASEM assembly site using copper (Cu) bond wire, YIZ8143 die attach and CEL 9240HF10AK-G1 molding compound material.

Post Change:

Assembled at MMT assembly site using palladium coated copper with gold flash (CuPdAu) bond wire, 3280 die attach and G600V molding compound material

Pre and Post Change Summary:

	Pre Change	**Post Change**
Assembly Site	ASE Group -Malaysia / ASEM	Microchip Technology Thailand (Branch) / MMT
Wire material	Cu	CuPdAu
Die attach material	YIZ8143	3280
Molding compound material	CEL 9240HF10AK-G1	G600V
Lead frame material	A194	A194

Impacts to Data Sheet:

None

Change Impact:

None

Reason for Change:

To improve manufacturability and on-time delivery by qualifying MMT as new assembly site

Change Implementation Status:

In Progress

Estimated Qualification Completion Date:

January 2020

Note: Please be advised the qualification completion times may be extended because of unforeseen business conditions however implementation will not occur until after qualification has completed and a final PCN has been issued. The final PCN will include the qualification report and estimated first ship date. Also note that after the estimated first ship date guided in the final PCN customers may receive pre and post change parts.

Time Table Summary:

	November 2019					-->	January 2020				
Workweek	44	45	46	47	48		01	02	03	04	05
Initial PCN Issue Date		X									
Qual Report Availability								X			
Final PCN Issue Date								X			

Method to Identify Change:

Traceability code

Qualification Plan:

Please open the attachments included with this PCN labeled as PCN_#_Qual_Plan.

Revision History:

November 08, 2019: Issued initial notification.

The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable products.

Attachment(s):

PCN_GBNG-04NNSN044_Qual_Plan.pdf

Please contact your local Microchip sales office with questions or concerns regarding this notification.

Terms and Conditions:

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If you wish to change your PCN profile, including opt out, please go to the PCN home page select login and sign into your myMicrochip account. Select a profile option from the left navigation bar and make the applicable selections.

Affected Catalog Part Numbers (CPN)

LE58QL031DJC
LE58QL021FJC
LE58QL02FJC
LE58QL031DJCT
LE58QL021FJCT
LE58QL02FJCT